

/ Revised record

/ Descriptions

0.8A MBF
0.8A Surface Mount Glass Passivated Bridge Rectifier, MBF thin package。

/ Features

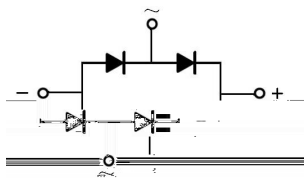
100V~1000V 0.8A

Glass Passivated Chip Junction, Reverse Voltage:100to1000V, Forward Current:0.8 A, High Surge Current Capability, Designed for Surface Mount Application, Halogen free product.

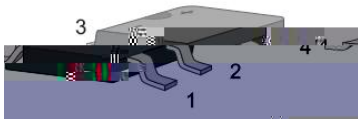
/ Applications

General purpose.

/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



/ Marking

See Marking Instructions.



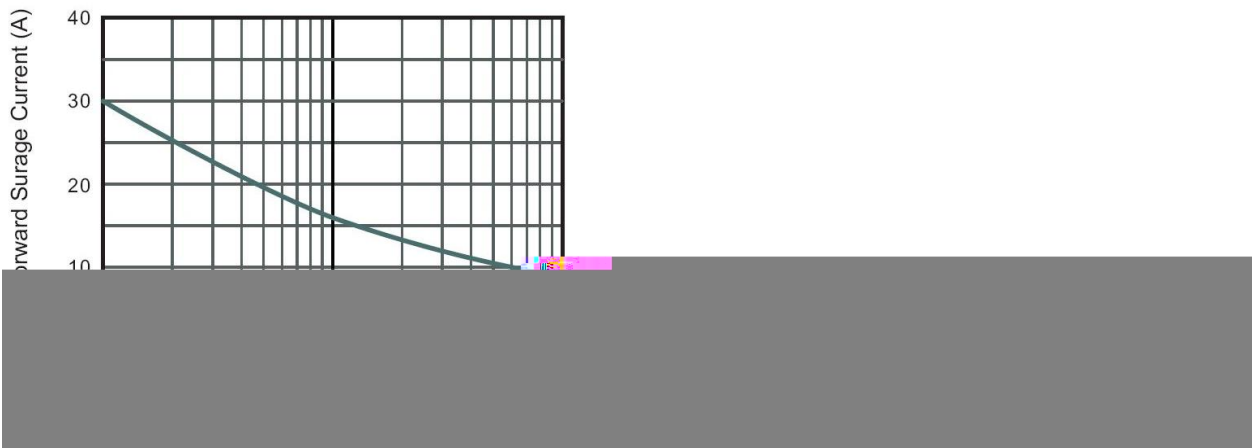
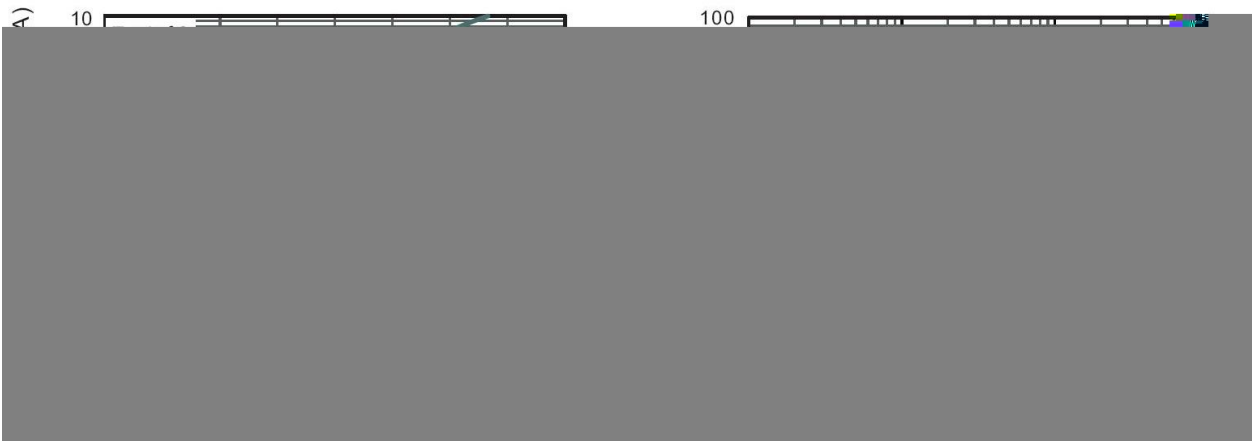
Parameter	Symbol	Rating						Unit
		MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 50℃	I _{F(AV)}	0.8						A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	30						A
Typical Junction Capacitance ¹⁾	C _j	13						pF
Typical Thermal Resistance ²⁾	R _{θJA}	95						℃/W
	R _{θJL}	30						
Operating and Storage Temperature Range	T _j ,T _{stg}	-55~+150						℃

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with $4 \times (5 \times 5 \text{mm}^2)$ copper pad.

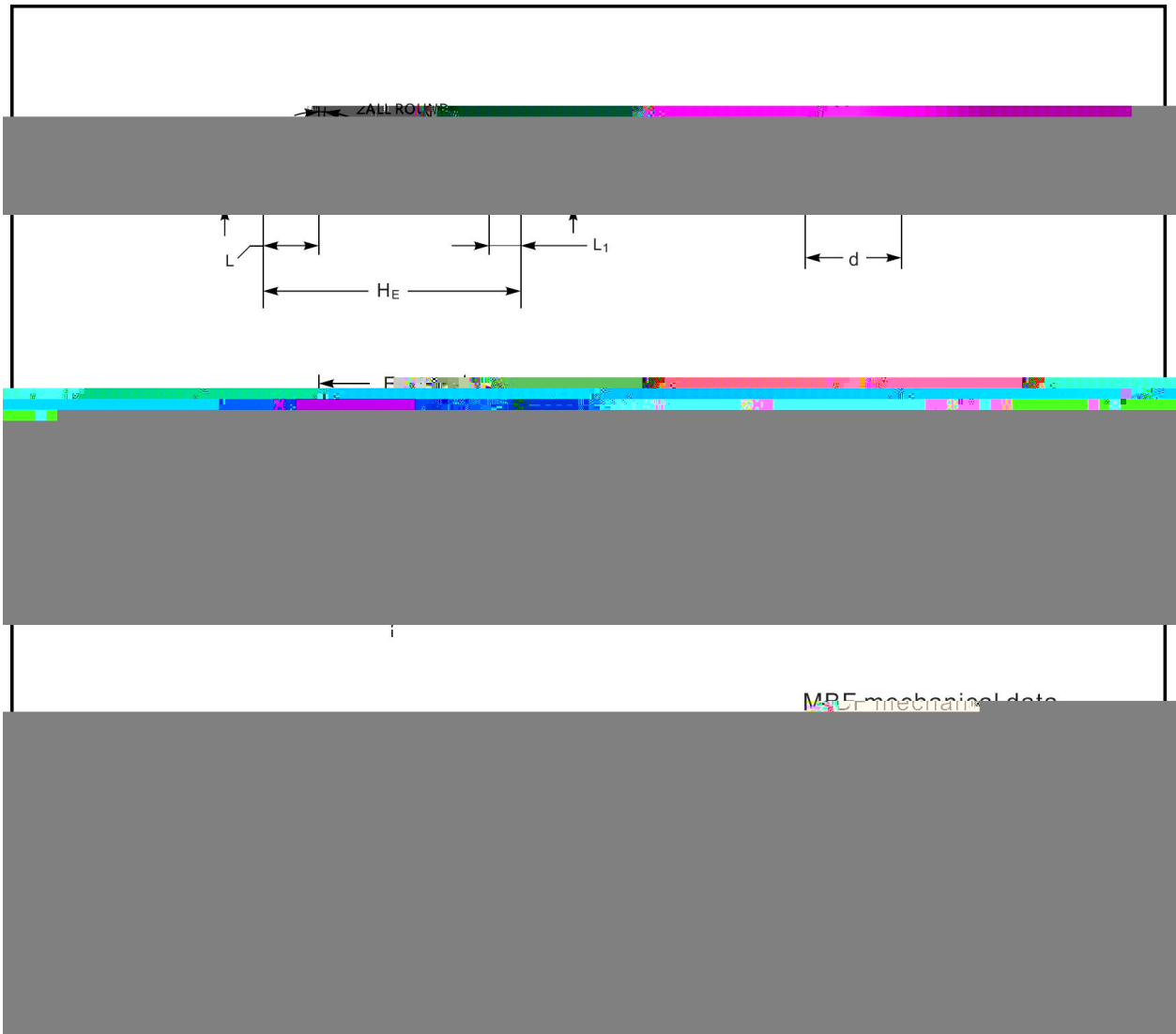
Parameter	Symbol	Test Conditions	数值 Rating	Unit
Max Instantaneous Forward Voltage	V_F	$I_F = 0.8\text{A}$	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a = 25^\circ\text{C}$	5.0	μA
		$T_a = 125^\circ\text{C}$	40	μA

/ Electrical Characteristic Curve



/ Package Dimensions

MBF

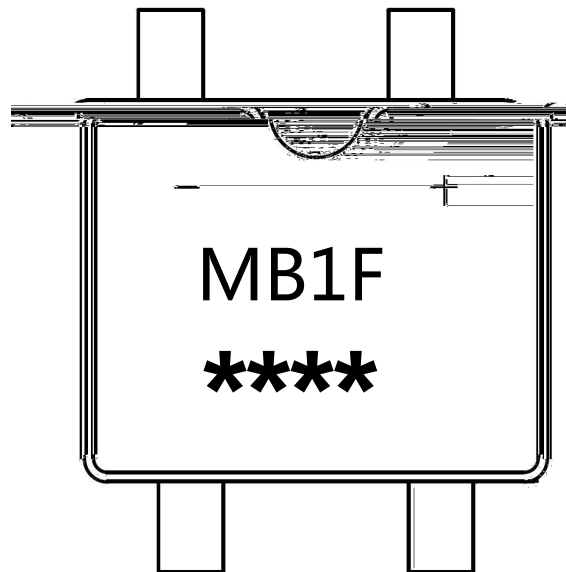


MB1F~MB10F

Rev.E Jan.-2021

DATA SHEET

/ Marking Instructions



MB1F

1 *

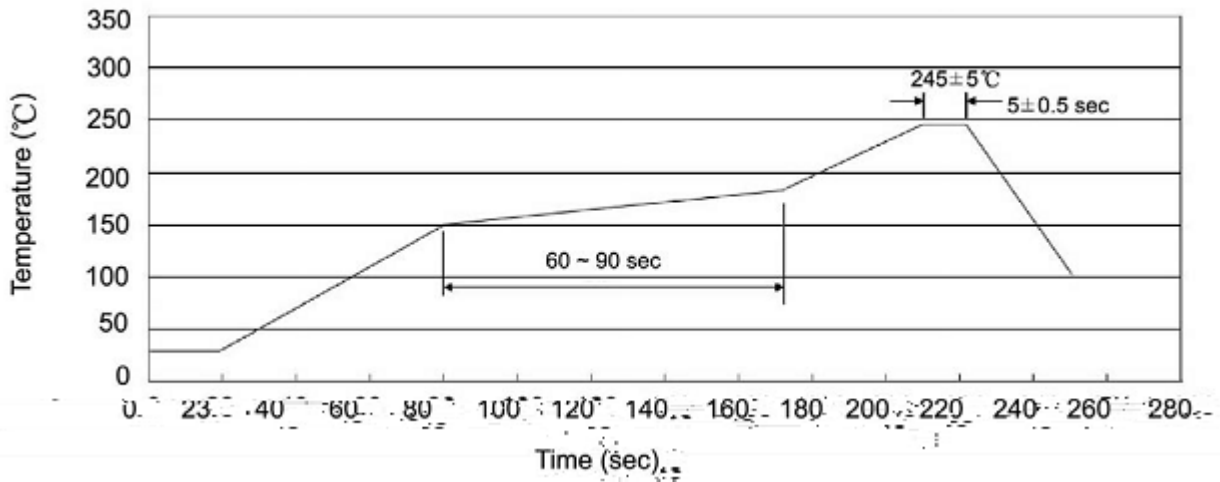
3 *

Note:

MB1F Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245 | 5 | 5 | 0.5sec; | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260	5	10	1 sec.	Temp.:260 5	Time:10 1 sec
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/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量	Dimension 包装尺寸 (unit: mm)	Y W
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